

AW869A

Dual band WiFi6 11ax+ BT5.4 Module Spec

(SDIO3.0, BW40M, 1-PIN antenna type, Shielding)

拟制 Design	审核 Check	批准 Approve	版本 Version	日期 Date
			V1.0	2024.07.22

更改记录

Reversion History

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1.0	2024.07.22	First release



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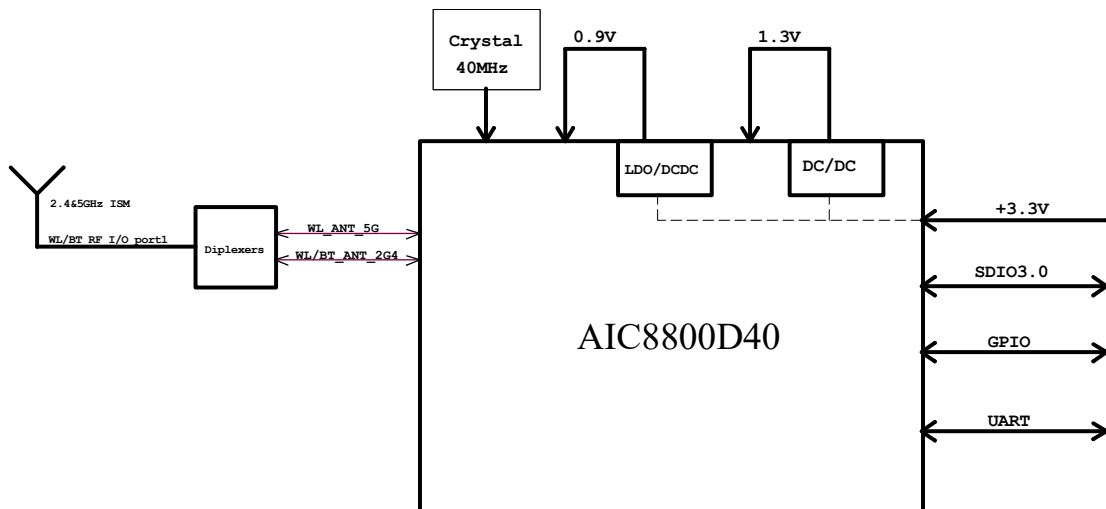
1. Overview

The AW869A is a highly integrated module with Dual band WiFi6,BT5.4; combination solution to support 1 × 1 IEEE 802.11a/b/g/n/ac/ax WLAN standards and BT 5.4 enabling seamless integration of WLAN/BT and low-energy technology.

2. Features

- Supports a low-power SDIO 3.0 interface for WLAN and a UART/PCM interface for BT
- Provides a highly integrated WLAN system-on-chip (SoC) for 5 GHz 802.11ac, or 2.4 GHz/5 GHz 802.11n WLAN applications
- Supports WLAN 2.4GHz and 5GHz , 20 MHz/40 MHz
- Supports BT 5.4, BLE, and ANT+ and backward compatibility with BT 1.x and BT 2.x + Enhanced Data Rate
- Supports a single-ended RF port for cleaner and lower cost design
- Supports STA,AP,WiFi Direct modes concurrently
- Supports WiFi6 TWT
- Supports MU-MIMO,OFDMA

3. Block Diagram



4. General Specification

Model	AW869A
Product Name	WLAN 802.11a/b/g/n/ac/ax SDIO3.0 1T1R + Bluetooth 5.4 module
Major Chipset	AIC8800D40
Standard	802.11a/b/g/n/ac/ax
Modulation Method	BPSK/ QPSK/ 16-QAM/ 64-QAM/256-QAM/1024-QAM
Frequency Band	Dual band 2.4GHz&5GHz ISM
WiFi Interface	SDIO3.0
BT Interface	UART
Operating Temperature	-20° C ~ 70° C
Storage Temperature	-20° C ~ 125°C
Humidity	5% to 90% maximum
Dimension	12x12x1.7 (LxWxH) ±0.2mm

5. RF Specification

5.1 2.4 GHz RF Specification

Feature	Description
WLAN Standard	IEEE 802.11b/g/n/ax WiFi compliant
Frequency Range	2.400 GHz ~ 2.497 GHz (2.4 GHz ISM Band)
Number of Channels	2.4GHz : Ch1 ~ Ch14
Modulation	802.11b : DQPSK, DBPSK, CCK 802.11 g/n : OFDM /64-QAM,16-QAM, QPSK, BPSK 802.11 ax : OFDMA /1024-QAM,256-QAM, 64-QAM, 16-QAM, QPSK, BPSK
Output Power	802.11b / 1Mbps : 17dBm ± 2 dB @ EVM ≤ -10dB 802.11b /11Mbps : 17dBm ± 2 dB @ EVM ≤ -15dB
	802.11g / 6Mbps : 17dBm ± 2 dB @ EVM ≤ -5dB 802.11g /54Mbps : 15 dBm ± 2 dB @ EVM ≤ -28dB
	802.11n /MCS0 : 16 dBm ± 2 dB @ EVM ≤ -5dB 802.11n /MCS7 : 14 dBm ± 2 dB @ EVM ≤ -34dB
	802.11ax /HE0(20/40M) : 16 dBm ± 2 dB @ EVM ≤ -5dB 802.11ax /HE11(20/40M) : 13 dBm ± 2 dB @ EVM ≤ -34dB
Receive Sensitivity (11b,20MHz) @8% PER	- 1Mbps PER @ -93 dBm, typical
	- 2Mbps PER @ -90 dBm, typical
	- 5.5Mbps PER @ -88 dBm, typical
	- 11Mbps PER @ -86 dBm, typical
Receive Sensitivity (11g,20MHz) @10% PER	- 6Mbps PER @ -91 dBm, typical
	- 9Mbps PER @ -89 dBm, typical
	- 12Mbps PER @ -86 dBm, typical
	- 18Mbps PER @ -83 dBm, typical
	- 24Mbps PER @ -80 dBm, typical
	- 36Mbps PER @ -77 dBm, typical
	- 48Mbps PER @ -74 dBm, typical
- 54Mbps PER @ -72 dBm, typical	
Receive Sensitivity (11n,20MHz) @10% PER	- MCS=0 PER @ -90 dBm, typical
	- MCS=1 PER @ -87 dBm, typical
	- MCS=2 PER @ -84 dBm, typical
	- MCS=3 PER @ -81 dBm, typical
	- MCS=4 PER @ -78 dBm, typical

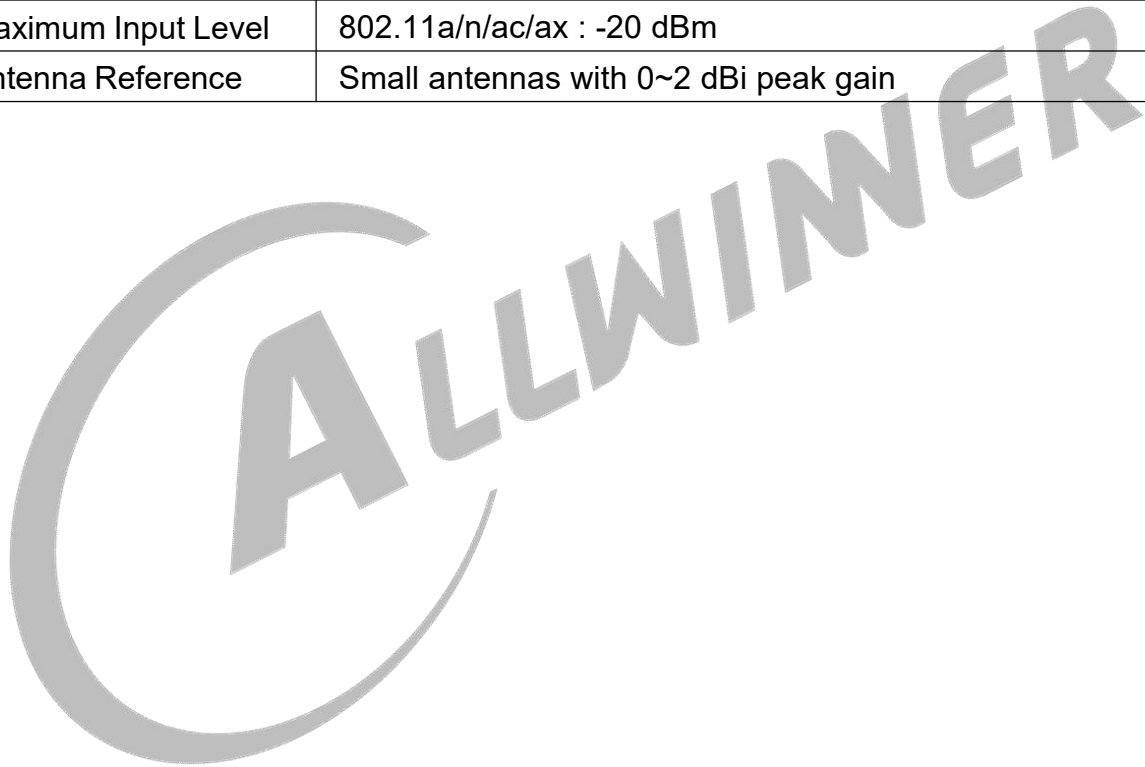
	- MCS=5 PER @ -75 dBm, typical
	- MCS=6 PER @ -72 dBm, typical
	- MCS=7 PER @ -70 dBm, typical
Receive Sensitivity (11n,40MHz) @10% PER	- MCS=0 PER @ -87 dBm, typical
	- MCS=1 PER @ -84 dBm, typical
	- MCS=2 PER @ -81 dBm, typical
	- MCS=3 PER @ -78 dBm, typical
	- MCS=4 PER @ -75 dBm, typical
	- MCS=5 PER @ -72 dBm, typical
	- MCS=6 PER @ -69 dBm, typical
	- MCS=7 PER @ -67 dBm, typical
Receive Sensitivity (11ax,20MHz) @10% PER	- HE=0 PER @ -90 dBm, typical
	- HE=1 PER @ -88 dBm, typical
	- HE=2 PER @ -86 dBm, typical
	- HE=3 PER @ -84 dBm, typical
	- HE=4 PER @ -81 dBm, typical
	- HE=5 PER @ -79 dBm, typical
	- HE=6 PER @ -76 dBm, typical
	- HE=7 PER @ -73 dBm, typical
	- HE=8 PER @ -70 dBm, typical
	- HE=9 PER @ -68 dBm, typical
Receive Sensitivity (11ax,40MHz) @10% PER	- HE=0 PER @ -88 dBm, typical
	- HE=1 PER @ -86 dBm, typical
	- HE=2 PER @ -83 dBm, typical
	- HE=3 PER @ -80 dBm, typical
	- HE=4 PER @ -77 dBm, typical
	- HE=5 PER @ -74 dBm, typical
	- HE=6 PER @ -72 dBm, typical
	- HE=7 PER @ -69 dBm, typical
	- HE=8 PER @ -66 dBm, typical
	- HE=9 PER @ -64 dBm, typical
Maximum Input Level	802.11b : -10 dBm
	802.11g/n/ax : -20 dBm
Antenna Reference	Small antennas with 0~2 dBi peak gain

5.2 5 GHz RF Specification

Feature	Description
WLAN Standard	IEEE 802.11a/n/ac/ax WiFi compliant
Frequency Range	4.900 GHz ~ 5.845 GHz (5.0 GHz ISM Band)
Number of Channels	5.0GHz: Please see the table
Modulation	802.11a : OFDM /64-QAM,16-QAM, QPSK, BPSK 802.11n : OFDM /64-QAM,16-QAM, QPSK, BPSK 802.11ac : OFDM /256-QAM
Output Power	802.11a / 6Mbps : 16 dBm ± 2 dB @ EVM ≤ -5dB 802.11a /54Mbps : 14 dBm ± 2 dB @ EVM ≤ -25dB
	802.11n HT20 /MCS0 : 16 dBm ± 2 dB @ EVM ≤ -5dB 802.11n HT20 /MCS7 : 13 dBm ± 2 dB @ EVM ≤ -28dB
	802.11n HT40 /MCS0 : 16 dBm ± 2 dB @ EVM ≤ -5dB 802.11n HT40 /MCS7 : 13dBm ± 2 dB @ EVM ≤ -28dB
	802.11ac VHT20 /MCS0 : 15 dBm ± 2 dB @ EVM ≤ -5dB 802.11ac VHT20 /MCS8 : 12 dBm ± 2 dB @ EVM ≤ -30dB
	802.11ac VHT40 /MCS0 : 15 dBm ± 2 dB @ EVM ≤ -5dB 802.11ac VHT40 /MCS9 : 12 dBm ± 2 dB @ EVM ≤ -32dB
	802.11ax HE0(20M) : 15 dBm ± 2 dB @ EVM ≤ -5dB 802.11ax HE11(20M) : 11 dBm ± 2 dB @ EVM ≤ -32dB
	802.11ax HE0(40M) : 15 dBm ± 2 dB @ EVM ≤ -5dB 802.11ax HE11(40M) : 11 dBm ± 2 dB @ EVM ≤ -32dB
Receive Sensitivity (11a,20MHz) @10% PER	- 6Mbps PER @ -93dBm, typical
	- 9Mbps PER @ -90 dBm, typical
	- 12Mbps PER @ -87 dBm, typical
	- 18Mbps PER @ -84 dBm, typical
	- 24Mbps PER @ -81 dBm, typical
	- 36Mbps PER @ -78 dBm, typical
	- 48Mbps PER @ -76 dBm, typical
- 54Mbps PER @ -74 dBm, typical	
Receive Sensitivity (11n,20MHz) @10% PER	- MCS=0 PER @ -92 dBm, typical
	- MCS=1 PER @ -89 dBm, typical
	- MCS=2 PER @ -86 dBm, typical
	- MCS=3 PER @ -83 dBm, typical
	- MCS=4 PER @ -80 dBm, typical
	- MCS=5 PER @ -77 dBm, typical
- MCS=6 PER @ -74 dBm, typical	

	- MCS=7 PER @ -72 dBm, typical
Receive Sensitivity (11n,40MHz) @10% PER	- MCS=0 PER @ -90 dBm, typical
	- MCS=1 PER @ -87 dBm, typical
	- MCS=2 PER @ -84 dBm, typical
	- MCS=3 PER @ -81 dBm, typical
	- MCS=4 PER @ -78 dBm, typical
	- MCS=5 PER @ -75 dBm, typical
	- MCS=6 PER @ -72 dBm, typical
	- MCS=7 PER @ -70 dBm, typical
Receive Sensitivity (11ac,20MHz) @10% PER	- MCS=0, NSS1 PER @ -91 dBm, typical
	- MCS=1, NSS1 PER @ -88 dBm, typical
	- MCS=2, NSS1 PER @ -85 dBm, typical
	- MCS=3, NSS1 PER @ -82 dBm, typical
	- MCS=4, NSS1 PER @ -79 dBm, typical
	- MCS=5, NSS1 PER @ -76dBm, typical
	- MCS=6, NSS1 PER @ -73 dBm, typical
	- MCS=7, NSS1 PER @ -70 dBm, typical
Receive Sensitivity (11ac,40MHz) @10% PER	- MCS=0, NSS1 PER @ -89 dBm, typical
	- MCS=1, NSS1 PER @ -86 dBm, typical
	- MCS=2, NSS1 PER @ -83 dBm, typical
	- MCS=3, NSS1 PER @ -80 dBm, typical
	- MCS=4, NSS1 PER @ -77 dBm, typical
	- MCS=5, NSS1 PER @ -74 dBm, typical
	- MCS=6, NSS1 PER @ -71 dBm, typical
	- MCS=7, NSS1 PER @ -68 dBm, typical
	- MCS=8, NSS1 PER @ -65 dBm, typical
	- MCS=9, NSS1 PER @ -63 dBm, typical
Receive Sensitivity (11ax,20MHz) @10% PER	- HE=0 PER @ -89 dBm, typical
	- HE=1 PER @ -86 dBm, typical
	- HE=2 PER @ -83 dBm, typical
	- HE=3 PER @ -80 dBm, typical
	- HE=4 PER @ -77 dBm, typical
	- HE=5 PER @ -74 dBm, typical
	- HE=6 PER @ -71 dBm, typical
	- HE=7 PER @ -68 dBm, typical

	- HE=8 PER @ -65 dBm, typical
	- HE=9 PER @ -63 dBm, typical
Receive Sensitivity (11ax,40MHz) @10% PER	- HE=0 PER @ -87 dBm, typical
	- HE=1 PER @ -84 dBm, typical
	- HE=2 PER @ -81 dBm, typical
	- HE=3 PER @ -78 dBm, typical
	- HE=4 PER @ -75 dBm, typical
	- HE=5 PER @ -72 dBm, typical
	- HE=6 PER @ -69 dBm, typical
	- HE=7 PER @ -66 dBm, typical
	- HE=8 PER @ -63 dBm, typical
	- HE=9 PER @ -61 dBm, typical
Maximum Input Level	802.11a/n/ac/ax : -20 dBm
Antenna Reference	Small antennas with 0~2 dBi peak gain



5.3 Bluetooth Section

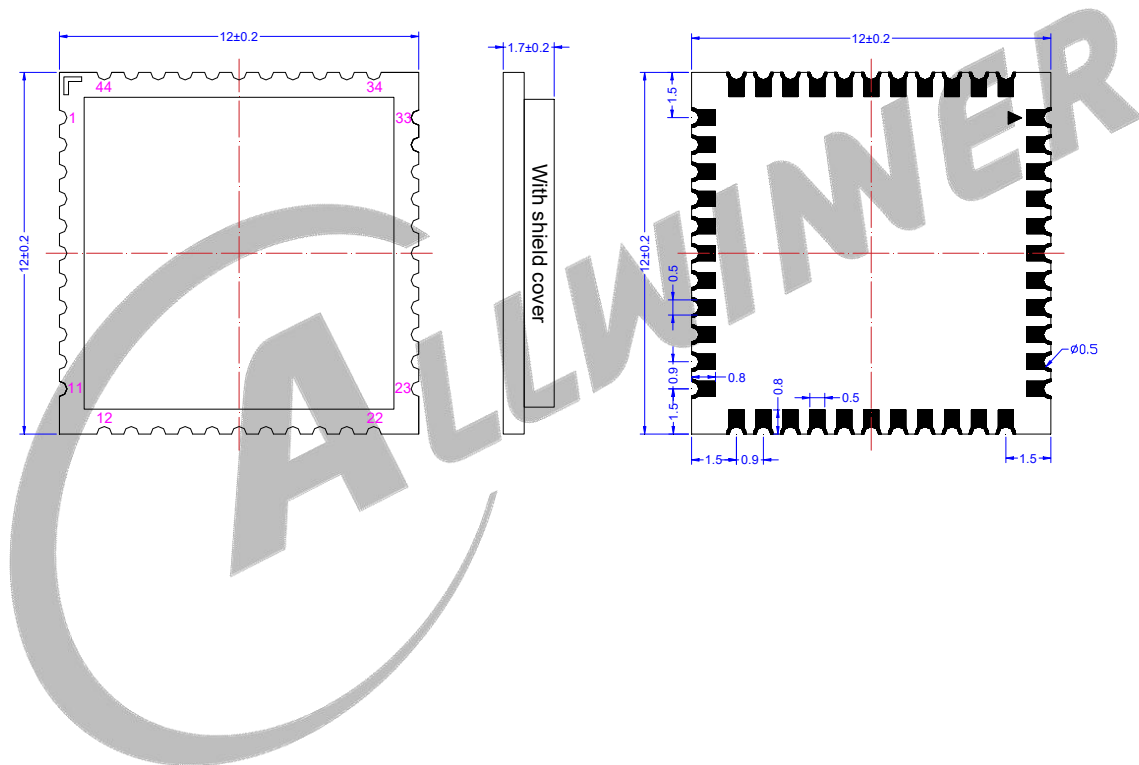
Feature	Description
General Specification	
Bluetooth Standard	Bluetooth V5.4 of 1, 2 and 3 Mbps.
Host Interface	UART
Antenna Reference	Small antennas with 0~2 dBi peak gain
Frequency Band	2402 MHz ~ 2480 MHz
Number of Channels	BR/EDR :79 channels;BLE:40 channels
Modulation	FHSS, GFSK, DPSK, DQPSK
RF Specification	
Output Power, tolerance \pm 2dBm	
BDR Output Power	8 dBm
EDR Output Power	8 dBm
BLE Output Power	8 dBm
Sensitivity, tolerance \pm 2dBm	
Sensitivity @ BER=0.1% for GFSK(1Mbps)	-96 dBm
Sensitivity @ BER=0.01% for $\pi/4$ -DQPSK(2Mbps)	-91 dBm
Sensitivity @ BER=0.01% for 8DPSK(3Mbps)	-89 dBm
Sensitivity @ BLE=30.8% for LE(1Mbps)	-100 dBm
Sensitivity @ BLE=30.8% for LE(2Mbps)	-90 dBm
Maximum Input Level	GFSK(1Mbps): -20 dBm
	$\pi/4$ -DQPSK(2Mbps): -20 dBm
	8DPSK(3Mbps): -20 dBm

6. Recommended Operating Rating

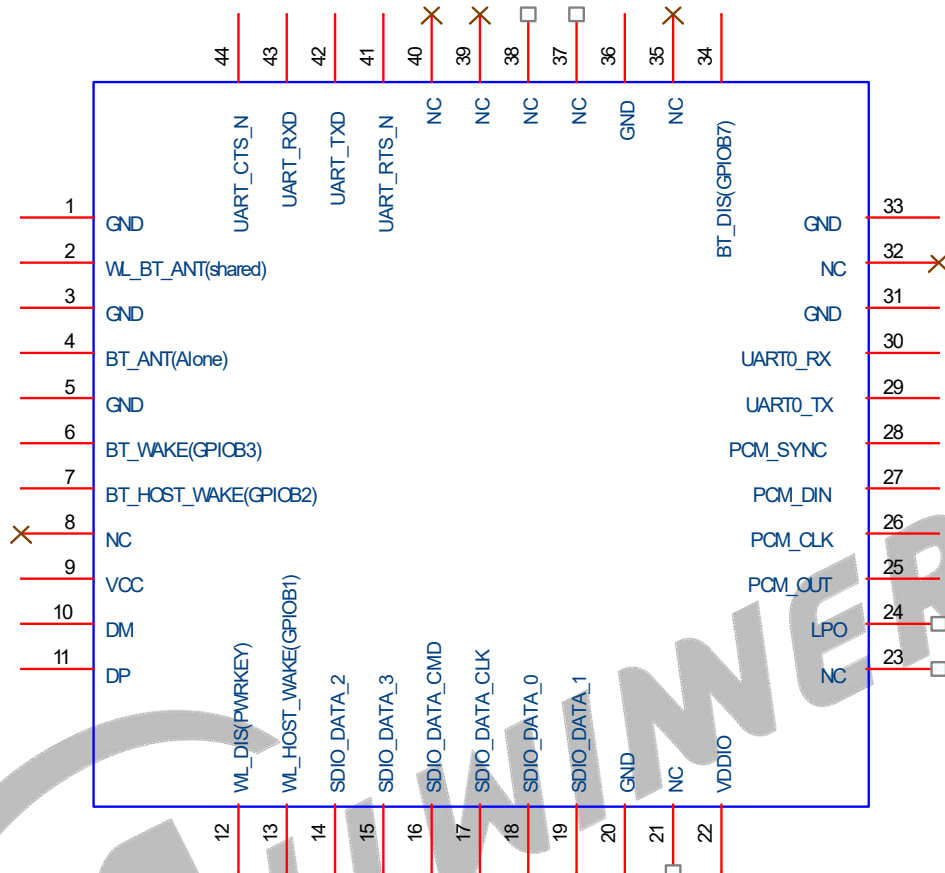
symbol	Parameter	Minimum	Typical	Maximum	Units
VDD	3.3V supply voltage	3.0	3.3	3.6	V
VDDIO	I/O supply voltage	1.7	1.8	1.9	V
Current	3.3V rating current	--	--	450	mA

7. Physical Dimensions

(Unit: mm)



8. Pin Description



NO.	Name	Type	Description
1	GND	—	Ground connections
2	RF	I/O	WL_BT RF I/O port (2.4/5GHz)
3	GND	—	Ground connections
4	NC	I/O	No connect, keep floati
5	GND	—	Ground connections
6	Host wake BT	I	Host wake BT(GPIOB3)
7	BT wake host	O	BT wake host (GPIOB2)
8	NC	—	No connect, keep floating
9	VDD	P	3.3V INPUT
10	USB_DM	—	No connect, keep floating
11	USB_DP	—	No connect, keep floating
12	WL_DIS	I	Power key (L=OFF, H=ON)
13	WL_Wake-up host	O	WL Wake-up host (GPIOB1)
14	SD_DAT2	I/O	SDIO DATA2
15	SD_DAT3	I/O	SDIO DATA3
16	SD_CMD	I/O	SDIO command line

17	SD_CLK	I/O	SDIO CLK
18	SD_DAT0	I/O	SDIO DATA0
19	SD_DAT1	I/O	SDIO DATA1
20	GND	—	Ground connections
21	NC	—	No connect, keep floating
22	VDDIO	P	I/O Voltage supply input 1.8V or 3.3V
23	NC	—	No connect, keep floating
24	LPO	—	No connect, keep floating
25	PCM OUT	O	PCM data output
26	PCM CLK	I/O	PCM CLK
27	PCM DIN	I	PCM data input
28	PCM SYNC	I	PCM sync signal
29	UART0_TX	—	No connect, keep floating(Debug pin)
30	UART0_RX	—	No connect, keep floating(Debug pin)
31	GND	—	Ground connections
32	NC	—	No connect, keep floating
33	GND	—	Ground connections
34	BT_DIS	—	Reserved (GPIOB7)
35	NC	—	No connect, keep floating
36	GND	—	Ground connections
37	NC	—	No connect, keep floating
38	NC	—	No connect, keep floating
39	NC	—	No connect, keep floating
40	NC	—	No connect, keep floating
41	UART_RTS	O	Bluetooth UART interface
42	UART_TX	O	Bluetooth UART interface
43	UART_RX	I	Bluetooth UART interface
44	UART_CTS	I	Bluetooth UART interface

备注：HFP(蓝牙通话)功能硬件采用 UART 接口

9. Supplier

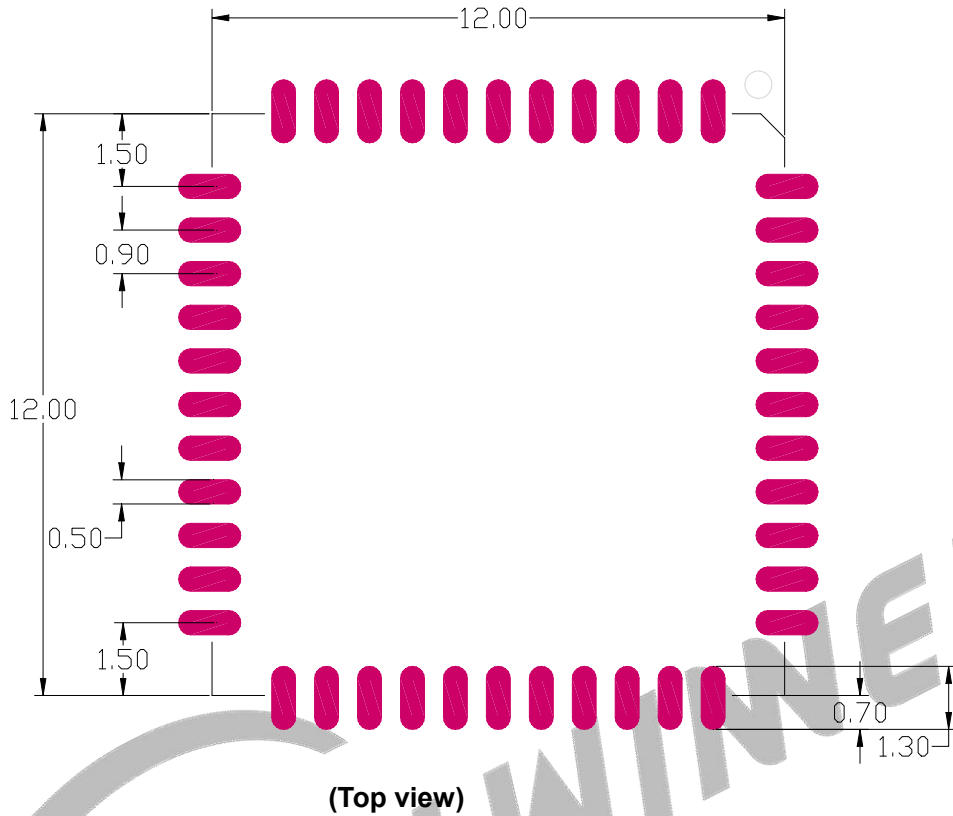
Supplier list	
Name of material	Material brand
Crystal	JWT/FK/TKD/Murata/TXC
Duplexer	ACX/GLEAD/Sunlord/Walsin
Inductor	Sunlord/ CHILISIN/ SAMWHA/Murata
Wifi chip	AIC
RF FEM	SAMSUNG /EYANG
RF switch	UniOhm /YAGEO
Capacitance	A,O,I,
Resistance	UniOhm /YAGEO
PCB(12x12x0.5mm)	A,O,I,F,D,T

10. Physical Photo



说明：PCB 不同供应商，底部丝印有微小差异

11. Layout Recommendation



12. Warpage



翘曲（间隙）的检验标准：

将模组放在水平大理石上，用 0.1mm 厚度的塞尺测量模组底部与大理石之间的间隙，要求 $gap \leq 0.12mm$ 。

13. Baking & Storage Temperature & Recommended Reflow Profile

(烘烤, 储存温度和推荐炉温)

13.1 Baking & Storage Temperature

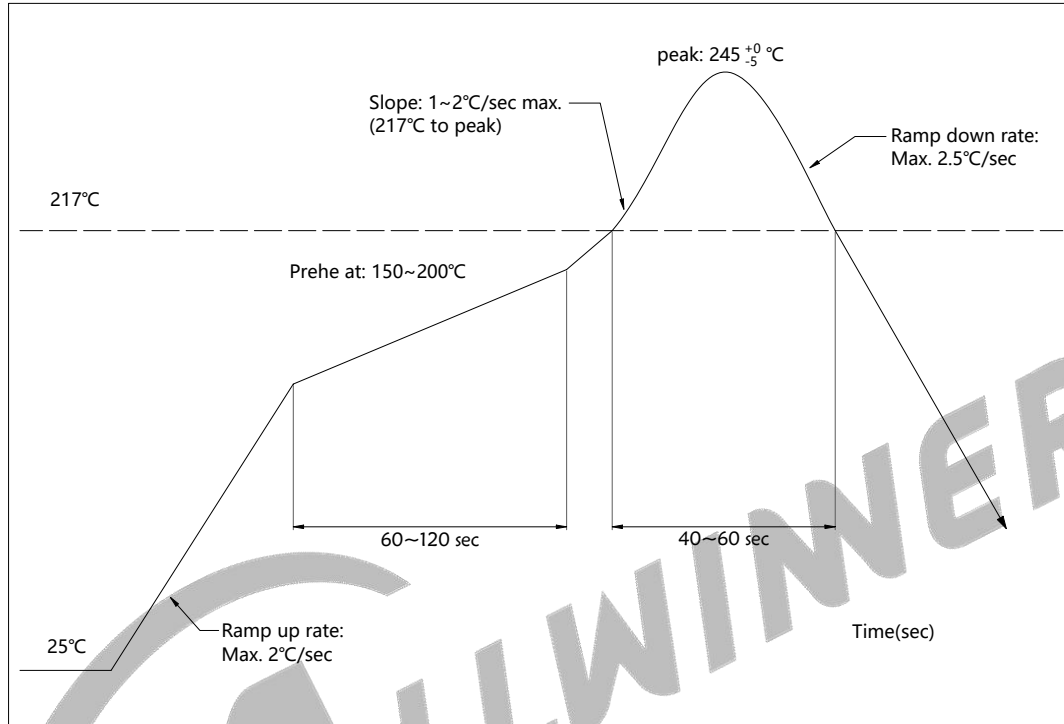
- Storage life: 12 months. Storage conditions: 40°C. Relative humidity: $90\% \text{R.H.}$
(保存期限: 12个月, 储存环境条件: 温度在: 40°C, 相对湿度: $90\% \text{R.H.}$)
- After this bag is opened, devices that will be subjected to infrared reflow, vapor-phase reflow, or equivalent processing must be .(模块包装被拆后, SMT 组装之时限)
 - ✓ Check the humidity card :stored at $\cong 20\% \text{RH}$. If :30%~40%(pink) or greater than 40%(red). Labeling module has moisture absorption. (检查湿度卡: 显示值应小于30% (蓝色), 如: 30%~40%(粉红色) 或者大于40% (红色) 表示模块已吸湿气.)
 - ✓ Mounted within 168 hours at factory conditions of: $t \cong 30^{\circ}\text{C}$, $\cong 60\% \text{R.H.}$
(工厂环境温度湿度管制: $\cong 30^{\circ}\text{C}$, $\cong 60\% \text{R.H.}$, 168小时内.)
 - ✓ Once opened, the workshop the preservation of life for 168 hours.
(拆封后, 车间的保存寿命为168小时.)
- Module apart packing after 168 hours, If baking is required, devices may be baked for.
(如在拆封后的168个小时内未使用完, 需要烘烤, 烘烤条件如下:)
 - ✓ Modules must be to remove module moisture problem. (模块须重新烘烤, 以除去模块吸湿问题.)
 - ✓ Baking temperature: $40^{\circ}\text{C} \pm 5^{\circ}\text{C}$, 120 hours. (烘烤温度条件: $40^{\circ}\text{C} \pm 5^{\circ}\text{C}$, 120小时).
 - ✓ After baking, put proper amount of desiccant to seal packages.
(烘烤后, 放入适量的干燥剂再密封包装)

13.2 Recommended Reflow Profile

Referred IPC/JEDEC standard.

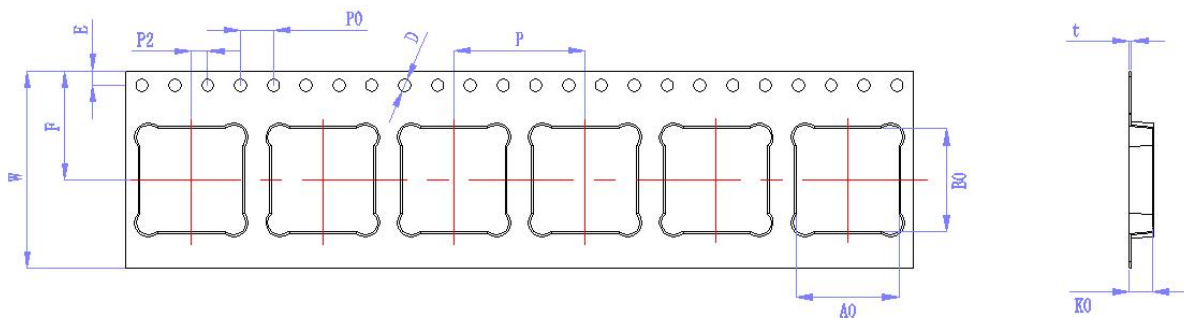
Peak Temperature : <250°C

Number of Times : 2 times



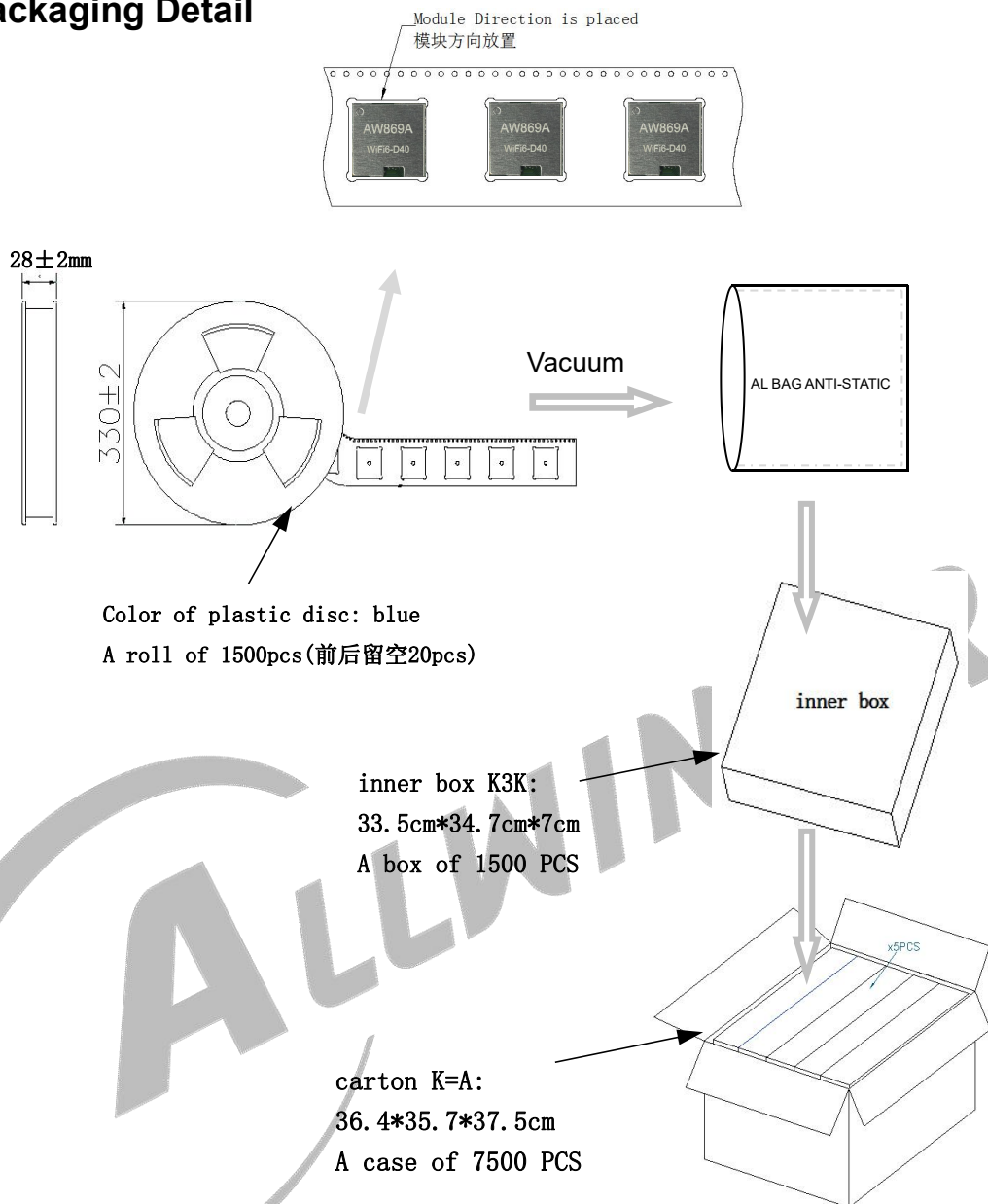
14. Packing information

14.1 Carrier Size Detail



ITEM	W	A0	B0	K0	P	F	E	D	P0	P2	T
DIM	24	12.5	12.5	2.8	16	13.25	1.75	1.50	4	2	0.3
TOLE	+0.30 -0.30	+0.10 -0.10	+0.10 -0.10	+0.10 -0.10	+0.10 -0.10	+0.10 -0.10	+0.10 -0.10	+0.10 -0.10	+0.10 -0.10	+0.10 -0.10	+0.05 -0.05

14.2 Packaging Detail



ESD CAUTION

The AW869A module is ESD (electrostatic discharge) sensitive device and may be damaged with ESD or spike voltage. Although AW869A module is with built-in ESD protection circuitry, please handle with care to avoid the permanent malfunction or the performance degradation.